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Subject: Re: stuffing choice by research

Posted by [Ka7niq](#) on Wed, 13 Jun 2007 21:50:28 GMT

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Here is an excerpt from the PatentSUMMARY OF THE INVENTION One object of the present invention is to provide an acoustic damping material which does not suffer from the limitations of the known art. A further object of one embodiment of the present invention is to provide a sound attenuating material suitable for use in a loudspeaker enclosure, comprising kapok material, the kapok for reducing enclosure resonance and driver resonance. The use of the kapok material is an alternative material that comes from the seed of kapok trees "Ceiba pentandra". This material is a natural fibrous material and is relatively inexpensive. The kapok material also has a very low density and thus is ideal for acoustic damping. By selection of the appropriate amount of kapok, the result is lower resonance within the enclosure. It has been found that by making use of the kapok that the resonance is greatly reduced relative to other materials. In addition, the kapok is essentially uninfluenced by the heat generated within the enclosure as the speaker drivers are used. This is in marked contrast to synthetic materials, particularly acoustic foam, which inherently would experience property changes due to thermal degradation.

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